

Advance Technical Information

GigaMOS™ Power MOSFET

IXFK120N30T IXFX120N30T

N-Channel Enhancement Mode Avalanche Rated Fast Intrinsic Diode

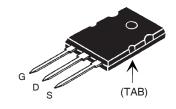


Symbol	Test Conditions	Maximum F	atings
V _{DSS}	$T_J = 25$ °C to 150°C	300	V
V _{DGR}	$T_J = 25$ °C to 150°C, $R_{GS} = 1M\Omega$	300	
V _{GSS}	Continuous	± 20	V
V _{GSM}	Transient	± 30	
I _{D25}	$T_{\rm C} = 25^{\circ}{\rm C}$	120	A
	$T_{\rm C} = 25^{\circ}{\rm C}$, Pulse Width Limited by $T_{\rm JM}$	330	A
I _A	$T_{c} = 25^{\circ}C$	30	A
E _{AS}	$T_{c} = 25^{\circ}C$	2.5	J
dV/dt	$I_{S} \le I_{DM}, V_{DD} \le V_{DSS}, T_{J} \le 150^{\circ}C$	20	V/ns
P _D	T _C = 25°C	960	W
T _J		-55 +150	0°
T _{JM}		150	0°
T _{stg}		-55 +150	0°
T _L	1.6mm (0.062 in.) from Case for 10s	300	°C
T _{SOLD}	Plastic Body for 10s	260	
M _d	Mounting Torque (TO-264)	1.13/10	Nm/lb.in.
F _c	Mounting Force (PLUS247)	20120 /4.527	N/lb.
Weight	TO-264	10	g
	PLUS247	6	g

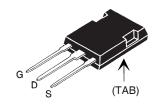
SymbolTest ConditionsCh $(T_J = 25^{\circ}C \text{ Unless Otherwise Specified})$ Mir			acteristic Values Typ. Max.		
BV _{DSS}	$V_{GS} = 0V, I_{D} = 3mA$	300			V
$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 4mA$	2.5		5.0	V
l _{GSS}	$V_{GS} = \pm 20V$, $V_{DS} = 0V$			± 200	nA
I _{DSS}	$V_{DS} = V_{DSS}, V_{GS} = 0V$ $T_{J} = 125^{\circ}C$			50 3	μA mA
R _{DS(on)}	$V_{GS} = 10V, I_{D} = 60A, Note 1$			24	mΩ

 $V_{DSS} = 300V$ $I_{D25} = 120A$ $R_{DS(on)} \le 24m\Omega$ $t_{rr} \le 200ns$

TO-264 (IXFK)



PLUS247 (IXFX)



G = Gate D = Drain S = Source TAB = Drain

Features

- International Standard Packages
- High Current Handling Capability
- Fast Intrinsic Diode
- Avalanche Rated
- Low R_{DS(on)}

Advantages

- Easy to Mount
- Space Savings
- High Power Density

Applications

- DC-DC Converters
- Battery Chargers
- Switched-Mode and Resonant-Mode Power Supplies
- DC Choppers
- AC Motor Drives
- Uninterruptible Power Supplies
- High Speed Power Switching Applications



•	Symbol Test Conditions Cha (T, = 25°C Unless Otherwise Specified) Min.		aracteristic Values Typ. Max.		5	
g _{fs}		$V_{DS} = 10V, I_{D} = 60A, Note 1$	70	120	max.	s
	<u> </u>	DS TOV, ID = GOT, IVERS T		20		nF
C _{iss}		V 0V V 05V £ 4MU-				
C_{oss}	ĺ	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		1380		pF
C _{rss}	J			135		pF
t _{d(on)})			32		ns
t _r	Ţ	Resistive Switching Times $V_{GS} = 15V, V_{DS} = 0.5 \cdot V_{DSS}, I_{D} = 0.5 \cdot I_{D25}$		31		ns
$\mathbf{t}_{d(off)}$		$R_{\rm g} = 10$ (External)		87		ns
t,	J			23		ns
$\mathbf{Q}_{\mathrm{g(on)}}$)			265		nC
\mathbf{Q}_{gs}	}	$V_{GS} = 10V$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_{D} = 0.5 \cdot I_{D25}$		87		nC
\mathbf{Q}_{gd}	J			60		nC
R _{thJC}					0.13	°C/W
$\mathbf{R}_{\mathrm{thCS}}$				0.15		°C/W

Source-Drain Diode

Symbol	Test Conditions	Cha	aracteristi	c Values	
$(T_J = 25^{\circ}C)$	C, Unless Otherwise Specified)	Min.	Тур.	Max.	
I _s	$V_{GS} = 0V$			120	Α
I _{SM}	Repetitive, Pulse Width Limited by $T_{_{JM}}$			480	Α
$\mathbf{V}_{\mathtt{SD}}$	$I_F = 60A, V_{GS} = 0V, Note 1$			1.5	V
t _{rr}	L 604 di/dt 1004/			200	ns
$\mathbf{Q}_{_{\mathrm{RM}}}$	$I_F = 60A$, $-di/dt = 100A/\mu s$ $V_R = 75V$, $V_{GS} = 0V$		0.8		μС
I _{RM}	$v_R = 75v$, $v_{GS} = 0v$		10.4		Α

Note 1: Pulse Test, $t \le 300\mu s$; Duty Cycle, $d \le 2\%$.

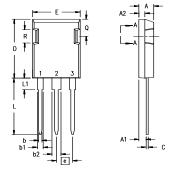
ADVANCE TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

TO-264 (IXFK) Outline

Dim.	Milli	meter	Inc	iches	
Diiii.	Min.	Max.	Min.	Max.	
Α	4.82	5.13	.190	.202	
A1	2.54	2.89	.100	.114	
A2	2.00	2.10	.079	.083	
b	1.12	1.42	.044	.056	
b1	2.39	2.69	.094	.106	
b2	2.90	3.09	.114	.122	
С	0.53	0.83	.021	.033	
D	25.91	26.16	1.020	1.030	
Е	19.81	19.96	.780	.786	
е	5.46 BSC		.215 BSC		
J	0.00	0.25	.000	.010	
K	0.00	0.25	.000	.010	
L	20.32	20.83	.800	.820	
L1	2.29	2.59	.090	.102	
Р	3.17	3.66	.125	.144	
Q	6.07	6.27	.239	.247	
Q1	8.38	8.69	.330	.342	
R	3.81	4.32	.150	.170	
R1	1.78	2.29	.070	.090	
S	6.04	6.30	.238	.248	
Т	1.57	1.83	.062	.072	

PLUS 247™ (IXFX) Outline



- Terminals: 1 Gate
 - 2 Drain (Collector)

 - 3 Source (Emitter) 4 Drain (Collector)

Dim.	Millimeter		Inches		
	Min.	Max.	Min.	Max.	
Α	4.83	5.21	.190	.205	
A ₁	2.29	2.54	.090	.100	
A ₂	1.91	2.16	.075	.085	
b	1.14	1.40	.045	.055	
b₁	1.91	2.13	.075	.084	
b ₂	2.92	3.12	.115	.123	
С	0.61	0.80	.024	.031	
D	20.80	21.34	.819	.840	
E	15.75	16.13	.620	.635	
е	5.45	BSC	.215 BSC		
L	19.81	20.32	.780	.800	
L1	3.81	4.32	.150	.170	
Q	5.59	6.20	.220	0.244	
R	4.32	4.83	.170	.190	

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.



Fig. 1. Output Characteristics @ 25°C

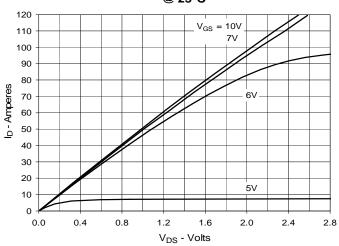


Fig. 2. Extended Output Characteristics @ 25°C

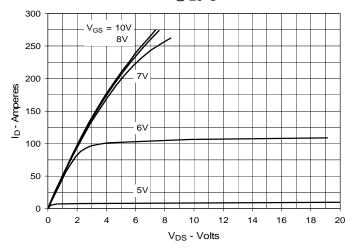


Fig. 3. Output Characteristics @ 125°C

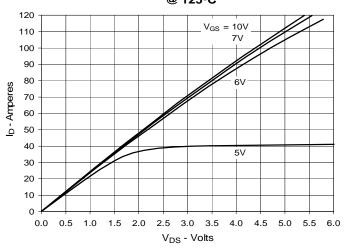


Fig. 4. $R_{DS(on)}$ Normalized to I_D = 60A Value vs. Junction Temperature

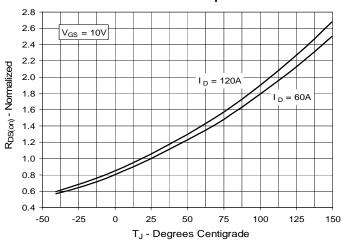


Fig. 5. $R_{DS(on)}$ Normalized to $I_D = 60A$ Value vs. Drain Current

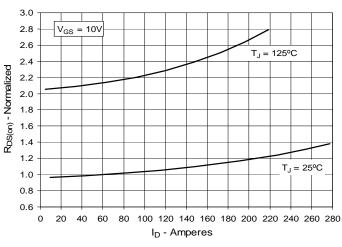
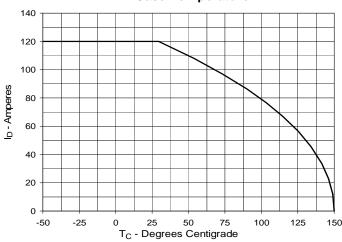


Fig. 6. Maximum Drain Current vs.

Case Temperature





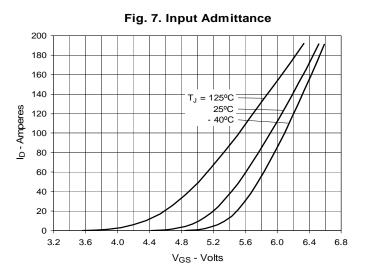
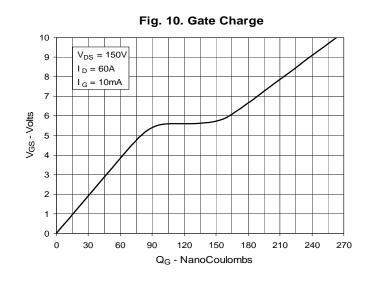
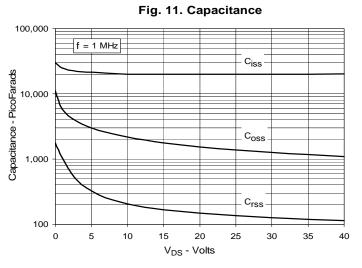


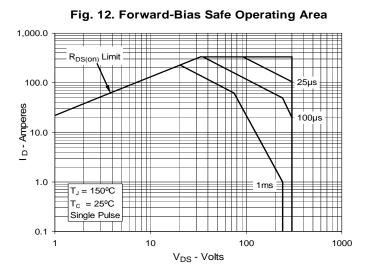
Fig. 8. Transconductance 200 $T_{J} = -40^{\circ}C$ 180 160 140 140 120 100 80 25ºC 125°C 60 40 20 0 0 20 40 60 80 100 120 140 160 180 200 I_D - Amperes

Intrinsic Diode 350 300 250 ls - Amperes 200 150 $T_{J} = 125^{\circ}C$ 100 $T_{J} = 25^{\circ}C$ 50 0 0.0 0.2 0.4 0.6 0.8 1.0 1.2 1.4 1.6 1.8 V_{SD} - Volts

Fig. 9. Forward Voltage Drop of

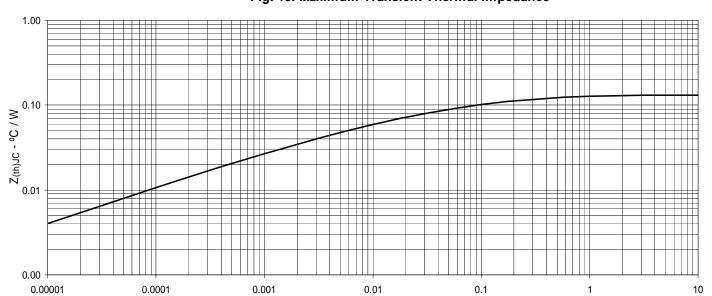






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Pulse Width - Seconds

Fig. 13. Maximum Transient Thermal Impedance

